

**METHODS AND APPARATUS FOR HOLDING AND POSITIONING SEMICONDUCTOR  
WORKPIECES DURING ELECTROPOLISHING AND/OR ELECTROPLATING OF THE  
WORKPIECES**

**ABSTRACT**

A cell to electroplate and/or electropolish semiconductor wafers includes an electrolyte receptacle and a wafer chuck assembly. The cell also includes a first actuator configured to translate the wafer chuck assembly between a first position and a second position, where the wafer chuck assembly covers the electrolyte receptacle in the first position and retracts from the electrolyte receptacle in the second position.